

REMARKS

The Applicants request reconsideration of the rejection.

Claims 15-20 remain pending.

Claims 15 and 18 were rejected under 35 USC §102(e) as being anticipated by Blanc, et al., US 6,437,985 (Blanc). The Applicants traverse as follows.

Claim 15 recites a method to mount an electronic circuit chip on a foldable rectangular sheet which has first and second sides, the second side being not wider than the first sides. The chip is mounted, according to the method, at a position which is not on any one of a line passing through positions of one-half of the length of the first sides and being parallel with the second sides, lines passing respectively through positions of one-third or one-fourth of the length of the first sides and being parallel with the second sides, and a line passing through positions of one-half of the second sides and being parallel with the first sides. In other words, the method is performed so that the chip is not mounted on specified lines, which is advantageous in that it preserves those lines for predetermined folds of the sheet, or even for common folds in the case where no configuration is previously known for the sheet. See page 6, line 27 through page 7, line 3 of the present specification.

Blanc discloses, in column 5, lines 51-53, that the interface support film 1 "must be able to be folded outside the zone of the chip for example into two or four." In the same column, at lines 56-57, Blanc teaches, "In other cases, it should be possible to crumple or crease at random, the folds having at least the radius quoted above" (less than 2.5 mm, and preferably less than 1 mm, as stated in line 55). Thus, Blanc does not limit the mounting of the chip so as to require the chip to be off the claimed lines.

The reason that Blanc does not so limit the location of the chip is supported in column 8, lines 2-6; namely, "The microcircuit is placed advantageously in a corner of the support film and directly above it. Preferably the choice is to position the chip in the corner of the label to reduce mechanical stresses linked to handling but also to have the largest possible surface free for printing." By this teaching, it appears that Blanc is concerned with "avoiding the chip", rather than "avoiding the fold" as in the present invention. At least, there is no suggestion that the fold lines themselves are of concern, particularly in light of the teaching that the sheet can be "crumpled at random."

Specifically, there seems to be no suggestion by Blanc that the chip should not be mounted on any one of the claimed lines:

a line passing through positions of one-half of the length of the first sides and being parallel with the second sides;

lines passing respectively through positions of one-third or one-fourth of the length of the first sides and being parallel with the second sides;

a line passing through positions of one-half of the second sides and being parallel with the first sides.

Claim 18 is similarly distinguishable from Blanc, requiring that "the electronic circuit chip is located at a position which is not on any one of a line passing through positions of one-half of the length of the first sides and being parallel with the second sides, lines passing respectively through positions of one-third or one-fourth of the length of the first sides and being parallel with the second sides, and a line passing through a position of one-half of the second sides and being parallel with the first sides."

Claim 18 was also rejected under 35 USC §102(b) as being anticipated by Kamiyama, JP 62-25096 (Kamiyama). Kamiyama, however, discloses that partial regions of a card body, in a crosswise direction and in a lengthwise direction intersected with each other and formed at the substantially central portion of the card body, become bent more easily than other regions. As a result, the semiconductor device of Kamiyama is embedded at a position of the card body excluding the above regions, so as to protect the device even if the card body is bent substantially due to an external force. See page 3, lines 16-24 of the attached translation of Kamiyama.

Kamiyama, thus, is not seen to teach or fairly suggest that the regions that are bent more easily are located on the lines as claimed. More particularly, it seems that Kamiyama is most concerned with being sure that the device is not located where the card is weakest, with such weaknesses not being defined as required by the claim, but rather at the substantially central portion of the card body one-by-one in a crosswise direction and in a lengthwise direction.

On the other hand, claim 18 recites a foldable rectangular sheet to which an electronic chip is mounted, characterized in that “the electronic circuit chip is located at a position which is not on any one of a line passing through positions of one-half of the length of the first sides and being parallel with the second sides, lines passing respectively through positions of one-third or one-fourth of the length of the first sides and being parallel with the second sides, and a line passing through a position of one-half of the second sides and being parallel with the first sides.” As noted above, this construction is advantageous in that, by not mounting the chip on specified lines, those lines are preserved for predetermined folds of the sheet, or even for common folds in the case where no configuration is previously known for the sheet. Thus, the electronic circuit chip of claim 18 can be prevented from being damaged without

reducing the expected usefulness of the sheet, simply by avoiding the mounting of the chip on the lines set forth in the claim which are typical locations for creases or folds.

In view of the foregoing amendments and remarks, the Applicants request reconsideration of the rejection and allowance of the claims.

To the extent necessary, Applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, or credit any overpayment of fees, to the deposit account of Mattingly, Stanger & Malur, P.C., Deposit Account No. 50-1417 (referencing attorney docket no. ASA-1003-02).

Respectfully submitted,

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